

PIC18(L)F25/26K83

PIC18(L)F25/26K83 Family Silicon Errata and Data Sheet Clarification

The PIC18(L)F25/26K83 family devices that you have received conform functionally to the current Device Data Sheet (DS40001943**B**), except for the anomalies described in this document.

The silicon issues discussed in the following pages are for silicon revisions with the Device and Revision IDs listed in Table 1. The silicon issues are summarized in Table 2.

The errata described in this document will be addressed in future revisions of the PIC18(L)F25/26K83 silicon.

Note: This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated in the last column of Table 2 apply to the current silicon revision (A3).

Data Sheet clarifications and corrections start on page 5, following the discussion of silicon issues.

The silicon revision level can be identified using the current version of MPLAB® IDE and Microchip's programmers, debuggers, and emulation tools, which are available at the Microchip corporate website (www.microchip.com).

For example, to identify the silicon revision level using MPLAB IDE in conjunction with a hardware debugger:

- 1. Using the appropriate interface, connect the device to the hardware debugger.
- 2. Open an MPLAB IDE project.
- 3. Configure the MPLAB IDE project for the appropriate device and hardware debugger.
- 4. Based on the version of MPLAB IDE you are using, do one of the following:
 - a) For MPLAB IDE 8, select <u>Programmer ></u> Reconnect.
 - b) For MPLAB X IDE, select <u>Window > Dashboard</u> and click the **Refresh Debug**Tool Status icon ().
- Depending on the development tool used, the part number and Device Revision ID value appear in the **Output** window.

Note: If you are unable to extract the silicon revision level, please contact your local Microchip sales office for assistance.

The DEVREV values for the various PIC18(L)F25/26K83 silicon revisions are shown in Table 1.

TABLE 1: SILICON DEVREY VALUES

Part Number	Device ID<13:0> ^{(1), (2)}	Revision ID for	Revision ID for Silicon Revision		
Part Number	Device ID~13.0>	A2	А3		
PIC18F25K83	6EE0h	A002	A003		
PIC18F26K83	6EC0h	A002	A003		
PIC18LF25K83	6F20h	A002	A003		
PIC18LF26K83	6F00h	A002	A003		

- **Note 1:** The Revision ID is located in addresses 3FFFFCh-3FFFDh and Device ID is located in addresses 3FFFFEh-3FFFFFh.
 - 2: Refer to the "PIC18(L)F25/26K83 *Memory Programming Specification*" (DS40001886) for detailed information on Device and Revision IDs for your specific device.

TABLE 2: SILICON ISSUE SUMMARY

Module	Feature	Item No.	Issue Summary	Affected Revisions ⁽¹⁾		
		NO.		A2	A3	
	SMBus 3.0	1.1	SMBus 3.0 logic levels.	Х	Х	
Electrical Specifications	Pecifications Reference (FVR) Accuracy 1.2 FVR output toler specified at temp		FVR output tolerance may be higher than specified at temperatures below 20°C.	X	х	
Direct Memory Access (DMA) Specifications	DMA in Doze mode	2.1	DMA transfers may not work when CPU is in Doze mode.	X		
Analog-to-Digital Converter Computation (ADC2)	Burst Average mode Double Sampling	3.1	The ADC ² does not trigger the second conversion when operated in non-continuous double-sampling Burst Average mode.	X		
Nonvolatile Memory (NVM) Control	WRERR bit Functionality	4.1	WRERR bit cannot be cleared in hardware after being set once.	х		
Windowed Watchdog Timer (WWDT)	WWDT Operation in Doze mode	5.1	Window violation occurs when WWDT is operated in Doze mode.	X		
Power-Saving Operation Modes	Low-Power Sleep mode	6.1	Low-Power Sleep mode does not operate at 3.1V <vdd <3.3v.<="" td=""><td>Х</td><td></td></vdd>	Х		
Program Flash Memory	Endurance of PFM Cell for LF Devices	7.1	Endurance of PFM cell is lower than specified	Х	Х	

Note 1: Only those issues indicated in the last column apply to the current silicon revision.

Silicon Errata Issues

Note:

This document summarizes all silicon errata issues from all revisions of silicon, previous as well as current. Only the issues indicated by the shaded column in the following tables apply to the current silicon revision (A3).

1. Module: Electrical Specifications

1.1 SMBus 3.0

The SMBus 3.0 VIL specification (Parameter D305) is temperature and VDD dependent. Refer to the table below.

Temperature	V DD	D305 SMBus 3.0 VIL Specification
-40°C	1.8V	0.6V
-40°C	5.5V	0.8V
25°C	1.8V	0.6V
25°C	5.5V	0.8V
85°C	1.8V	0.6V
85°C	5.5V	0.6V
125°C	1.8V	0.5V
125°C	5.5V	0.6V

Work around

None.

Affected Silicon Revisions

A2	А3			
Χ	Χ			

1.2 Fixed Voltage Reference (FVR) Accuracy

At temperatures below -20°C, the output voltage for the FVR may be greater than the levels specified in the data sheet. This will apply to all three gain amplifier settings (1X, 2X, 4X). The affected parameter numbers found in the data sheet are: FVR01 (1X gain setting), FVR02 (2X gain setting), and FVR03 (4X gain setting).

Work around

At temperatures above -20°C, the stated tolerances in the data sheet remain in effect. Operate the FVR only at temperatures above -20°C.

Affected Silicon Revisions

A2	А3			
Χ	Х			

2. Module: Direct Memory Access (DMA) Specifications

2.1 DMA in Doze Mode 3.0

When the CPU is operated in Doze mode, DMA transfers may not work as expected.

Work around

None.

Affected Silicon Revisions

A2	А3			
Χ				

3. Module: Analog-to-Digital Converter Computation (ADC²)

3.1 Burst Average Mode Double Sampling

When the ADC^2 is operated in Burst Average mode (MD = 0 ± 0.011 in the ADCON2 register) while enabling non-continuous operation and double-sampling (CONT = 0 in the ADCON0 register and DSEN = 1 in the ADCON1 register), the value in the ADCNT register does not increment beyond 0 ± 1 toward the value in the ADRPT register.

Work around

When operating the ADC^2 in Burst Average mode with double-sampling, enable continuous operation of the module (CONT = 1 in the ADCON0 register) and set the Stop-On-Interrupt bit (SOI bit in the ADCON3 register). After the interrupt occurs, perform appropriate threshold calculations in the software and re-trigger ADC^2 as necessary.

If the CPU is in Low-Power Sleep mode, alternatively the ADC^2 in non-continuous Burst Average mode can be operated with single ADC conversion (DSEN = 0 in the ADCON1 register), compromising noise immunity for lower power consumption by preventing the device from waking up to perform threshold calculations in software.

Affected Silicon Revisions

A2	2	А3			
X					

4. Module: Nonvolatile Memory (NVM) Control

4.1 WRERR Bit Functionality

When a Reset is issued while an NVM high-voltage operation is in progress, the WRERR bit in the NVMCON1 register is set as expected. After clearing the WRERR bit, if a Reset reoccurs, the WRERR bit is set again, regardless of whether an NVM operation is in progress or not.

Work around

None.

Affected Silicon Revisions

A2	А3			
Χ				

5. Module: Windowed Watchdog Timer (WWDT)

5.1 WWDT Operation in Doze Mode

When the CLRWDT instruction is issued in Doze mode, a window violation error occurs in WWDT, even though the window is open and armed.

Work around

Do not operate the WWDT in Doze mode.

Affected Silicon Revisions

A2	А3			
Х				

6. Module: Power-Saving Operation Modes

6.1 Low-Power Sleep Mode in F Devices

When the CLRWDT instruction is issued in Doze mode, a window violation error occurs in WWDT, even though the window is open and armed.

Work around

a) If wake-up from Sleep is needed at $3.1V < V_{DD} < 3.3V$, operate the F device in Normal Power mode (VREGPM = 0).

b) If wake-up from Sleep is needed at 3.1V < VDD < 3.3V, enable the Fixed Voltage Reference (EN = 1 in the FVRCON register). This increases the current in Sleep mode by typically 7 μ A.

Affected Silicon Revisions

A2	А3			
Х				

7. Module: Program Flash Memory

7.1 Endurance of PFM Cell for LF Devices

The Flash memory cell endurance specification (Parameter MEM30) for this device family is 1K cycles.

Work around

None.

A2	А3			
Х	Х			

Data Sheet Clarifications

The following typographic corrections and clarifications are to be noted for the latest version of the device data sheet (DS40001943**B**):

Note: Corrections are shown in **bold**. Where possible, the original bold text formatting has been removed for clarity.

1. Module: Min. VDD Specification for LF Devices

VDDMIN for LF devices has changed for temperatures below +25°C as shown below in **bold**.

PIC18LF	25/26K83	3	Standa	ard Oper	ating Co	ndition	s (unless otherwise stated)		
PIC18F2	25/26K83								
Param. No. Characteristic		Min.	Тур.†	Max.	Units	Conditions			
Supply Voltage									
D002	VDD		2.3 1.8 2.5 2.7	_ _ _	3.6 3.6 3.6 3.6	V V V	Fosc ≤ 16 MHz (-40°C to <+25°C) Fosc ≤ 16 MHz (≥+25°C to +125°C) Fosc > 16 MHz and Fosc ≤ 32 MHz Fosc > 32 MHz		
D002	VDD		2.3 2.5 3.0	_ _ _	5.5 5.5 5.5	V V V	Fosc ≤ 16 MHz Fosc > 16 MHz and Fosc ≤ 32 MHz Fosc > 32 MHz		

APPENDIX A: DOCUMENT REVISION HISTORY

Rev C Document (1/2020)

Removed Module 1.2, renumbered Module 1.3 and updated; Updated Table 2.

Data Sheet Clarifications:

Added Module 1.

Rev B Document (2/2019)

Added silicon revision A3.

Added Module 1.3: Fixed Voltage Reference (FVR) Accuracy. Added Module 2: Direct Memory Access (DMA). Added Module 3: Analog-to-Digital Converter with Computation (ADC²). Added Module 4: Nonvolatile Memory (NVM) Control. Added Module 5: Windowed Watchdog Timer (WWDT). Added Module 6: Power-Saving Operation Modes. Added module 7: Program Flash Memory.

Rev A Document (11/2017)

Initial release of this document.

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 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
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